

# GaN Power Transistor, 28 V, 5 W DC - 6 GHz



NPTB00004B

Rev. V1

## Features

- GaN on Si HEMT D-Mode Transistor
- Suitable for linear and saturated applications
- Tunable from DC - 6 GHz
- 28 V Operation
- 14.8 dB Gain @ 2.5 GHz
- 57 % Drain Efficiency @ 2.5 GHz
- 100 % RF Tested
- Industry standard SOIC plastic package
- RoHS\* Compliant

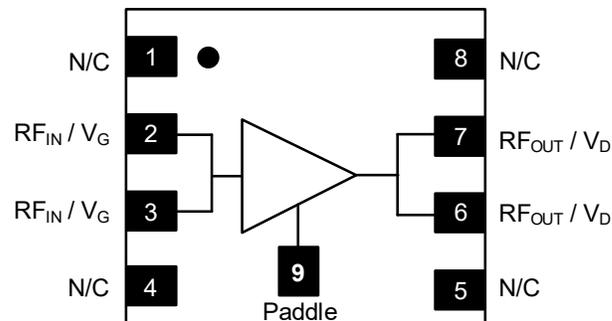
## Applications

- Defense Communications
- Land Mobile Radio
- Avionics
- Wireless Infrastructure
- ISM
- VHF/UHF/L/S-Band Radar

## Description

The NPTB00004B GaN HEMT is a power transistor optimized for DC - 6 GHz operation. This device supports CW, pulsed, and linear operation with output power levels to 5 W (37 dBm) in an industry standard surface mount plastic package.

## Functional Schematic



## Pin Configuration

Pin #	Pin Name	Function
1, 4, 5, 8	N/C	No Connection
2, 3	RF <sub>IN</sub> / V <sub>G</sub>	RF Input / Gate
6, 7	RF <sub>OUT</sub> / V <sub>D</sub>	RF Output / Drain
9	Paddle <sup>1</sup>	Ground / Source

1. The exposed pad centered on the package bottom must be connected to RF and DC ground. This path must also provide a low thermal resistance heat path.

## Ordering Information

Part Number	Package
NPTB00004B	Bulk Quantity
NPTB00004B-SMB	Sample Board
NPTB00004B-TR0500	Tape and Reel

\* Restrictions on Hazardous Substances, compliant to current RoHS EU directive.

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## RF Electrical Specifications: $T_C = 25^\circ\text{C}$ , $V_{DS} = 28\text{ V}$ , $I_{DQ} = 50\text{ mA}$

Parameter	Test Conditions	Symbol	Min.	Typ.	Max.	Units
Small Signal Gain	CW, 2.5 GHz	$G_{SS}$	-	16	-	dB
Saturated Output Power	CW, 2.5 GHz	$P_{SAT}$	-	37.1	-	dBm
Drain Efficiency at Saturation	CW, 2.5 GHz	$\eta_{SAT}$	-	63.7	-	%
Power Gain	2.5 GHz, $P_{OUT} = 4\text{ W}$	$G_P$	12.8	14.8	-	dB
Drain Efficiency	2.5 GHz, $P_{OUT} = 4\text{ W}$	$\eta$	45	57	-	%
Ruggedness: Output Mismatch	All phase angles	$\Psi$	VSWR = 15:1, No Device Damage			

## DC Electrical Characteristics: $T_C = 25^\circ\text{C}$

Parameter	Test Conditions	Symbol	Min.	Typ.	Max.	Units
Drain-Source Leakage Current	$V_{GS} = -8\text{ V}$ , $V_{DS} = 100\text{ V}$	$I_{DLK}$	-	-	2	mA
Gate-Source Leakage Current	$V_{GS} = -8\text{ V}$ , $V_{DS} = 0\text{ V}$	$I_{GLK}$	-	-	1	mA
Gate Threshold Voltage	$V_{DS} = 28\text{ V}$ , $I_D = 2\text{ mA}$	$V_T$	-3.0	-2.1	-1.0	V
Gate Quiescent Voltage	$V_{DS} = 28\text{ V}$ , $I_D = 50\text{ mA}$	$V_{GSQ}$	-2.6	-1.8	-0.8	V
On Resistance	$V_{DS} = 2\text{ V}$ , $I_D = 15\text{ mA}$	$R_{ON}$	-	1.6	-	$\Omega$
Maximum Drain Current	$V_{DS} = 7\text{ V}$ pulsed, pulse width 300 $\mu\text{s}$	$I_{D,MAX}$	-	1.4	-	A

### Absolute Maximum Ratings<sup>2,3,4,5,6</sup>

Parameter	Absolute Maximum
Drain Source Voltage, $V_{DS}$	100 V
Gate Source Voltage, $V_{GS}$	-10 to 3 V
Gate Current, $I_G$	4 mA
Storage Temperature Range	-65°C to +150°C
Case Operating Temperature Range	-40°C to +85°C
Channel Operating Temperature Range, $T_{CH}$	-40°C to +225°C
Absolute Maximum Channel Temperature	+250°C

2. Exceeding any one or combination of these limits may cause permanent damage to this device.
3. MACOM does not recommend sustained operation near these survivability limits.
4. Operating at drain source voltage  $V_{DS} < 32$  V will ensure  $MTTF > 1 \times 10^7$  hours.
5. Operating at nominal conditions with  $T_{CH} \leq 225^\circ\text{C}$  will ensure  $MTTF > 1 \times 10^7$  hours.
6.  $MTTF$  may be estimated by the expression  $MTTF$  (hours) =  $A e^{[B + C/(T+273)]}$  where T is the channel temperature in degrees Celsius, A = 3.686, B = -35.00, and C = 25.416.

### Thermal Characteristics<sup>7</sup>

Parameter	Test Conditions	Symbol	Typical	Units
Thermal Resistance	$V_{DS} = 28$ V, $T_J = 180^\circ\text{C}$	$R_{\theta JC}$	15	°C/W

7. Junction temperature ( $T_J$ ) measured using IR Microscopy. Case temperature measured using thermocouple embedded in heat-sink.

### Handling Procedures

Please observe the following precautions to avoid damage:

### Static Sensitivity

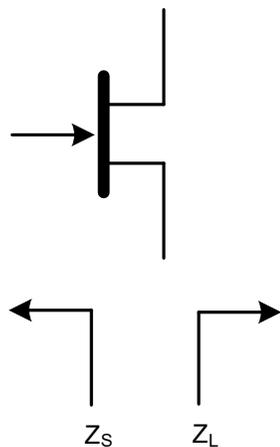
Gallium Nitride Circuits are sensitive to electrostatic discharge (ESD) and can be damaged by static electricity. Proper ESD control techniques should be used when handling these HBM Class 1A devices.

**Load-Pull Performance:  $V_{DS} = 28\text{ V}$ ,  $I_{DQ} = 50\text{ mA}$ ,  $T_C = 25^\circ\text{C}$**

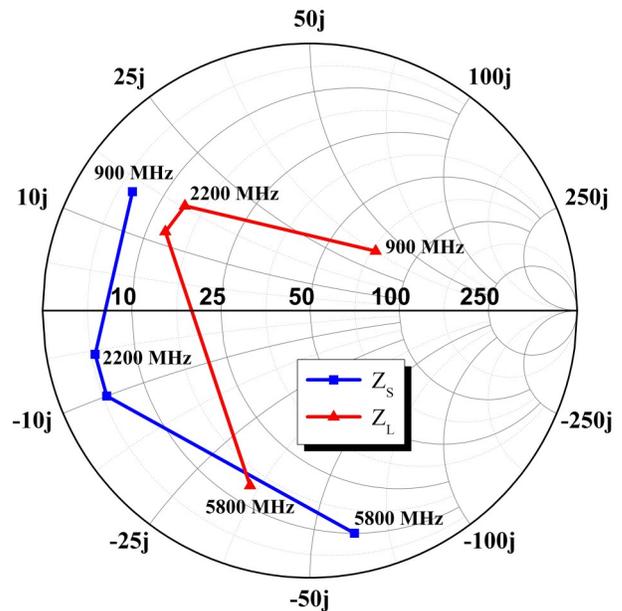
Reference Plane at Device Leads, CW Drain Efficiency and Output Power Tradeoff Impedance

Frequency (MHz)	$Z_S$ ( $\Omega$ )	$Z_L$ ( $\Omega$ )	$P_{SAT}$ (W)	$G_{SS}$ (dB)	Drain Efficiency @ $P_{SAT}$ (%)
900	$6.1 + j15$	$72 + j36$	7.0	23.0	68
2200	$5.0 - j5.0$	$14 + j17$	6.7	19.0	66
2700	$5.0 - j10$	$13 + j12$	6.7	17.0	62
5800	$10 - j60$	$14 - j34$	6.5	52	

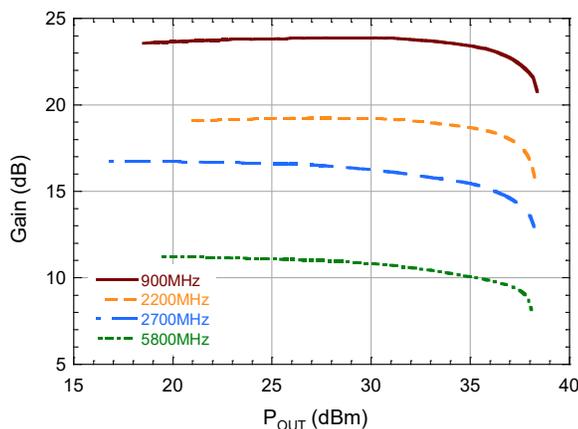
**Impedance Reference**



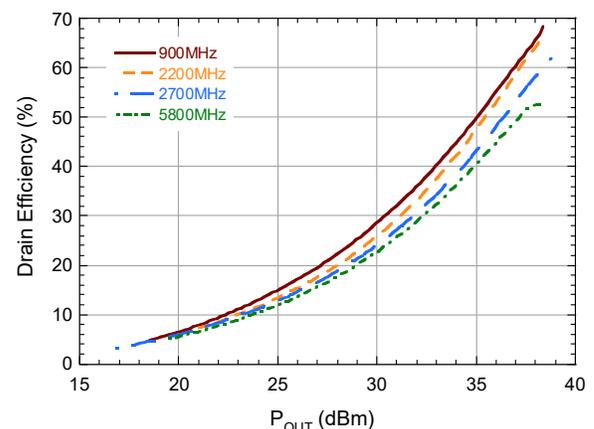
**$Z_S$  and  $Z_L$  vs. Frequency**



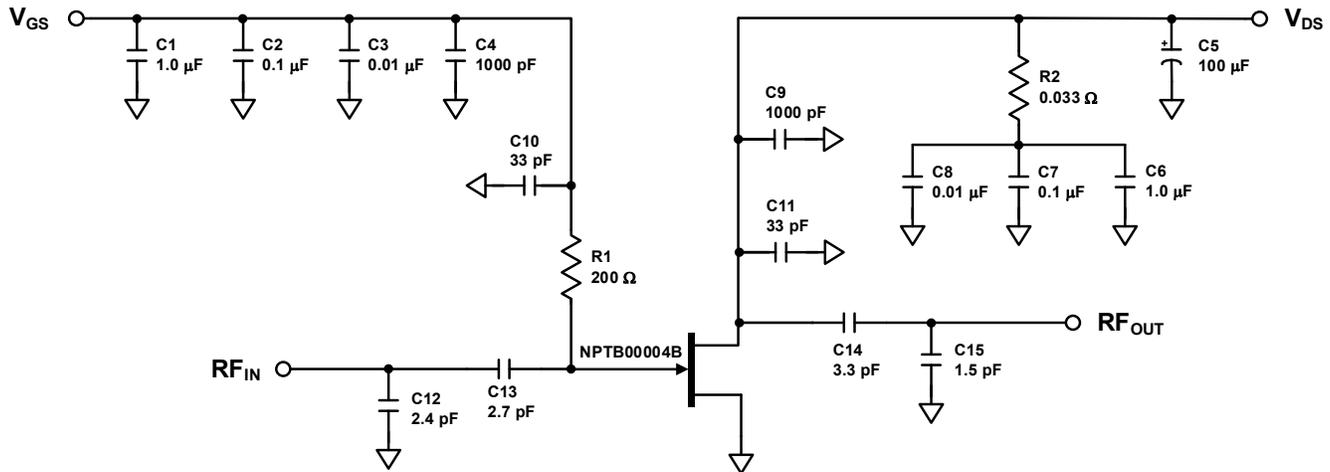
**Gain vs. Output Power**



**Drain Efficiency vs. Output Power**



**Evaluation Board and Recommended Tuning Solution**  
2.5 GHz Narrowband Circuit



**Description**

Parts measured on evaluation board (20-mil thick RO4350). The PCB's electrical and thermal ground is provided using a standard-plated densely packed via hole array (see recommended via pattern).

Matching is provided using a combination of lumped elements and transmission lines as shown in the simplified schematic above. Recommended tuning solution component placement, transmission lines, and details are shown on the next page.

**Bias Sequencing**

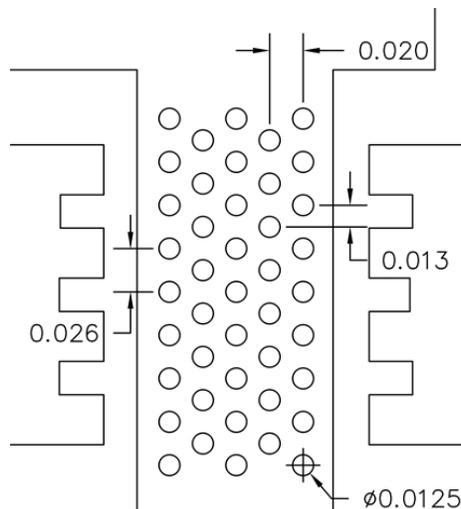
**Turning the device ON**

1. Set  $V_{GS}$  to the pinch-off ( $V_P$ ), typically -5 V.
2. Turn on  $V_{DS}$  to nominal voltage (28 V).
3. Increase  $V_{GS}$  until the  $I_{DS}$  current is reached.
4. Apply RF power to desired level.

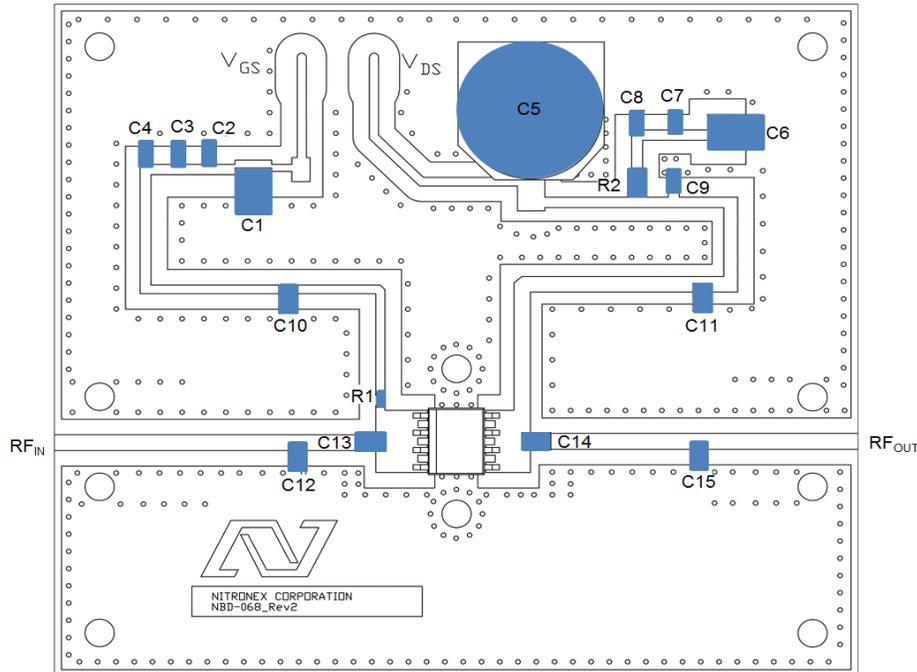
**Turning the device OFF**

1. Turn the RF power off.
2. Decrease  $V_{GS}$  down to  $V_P$ .
3. Decrease  $V_{DS}$  down to 0 V.
4. Turn off  $V_{GS}$ .

**Recommended Via Pattern (All dimensions shown as inches)**



**Evaluation Board and Recommended Tuning Solution**  
2.5 GHz Narrowband Circuit

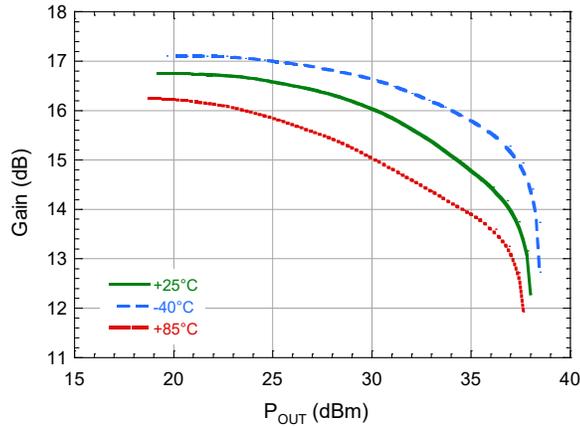


**Parts list**

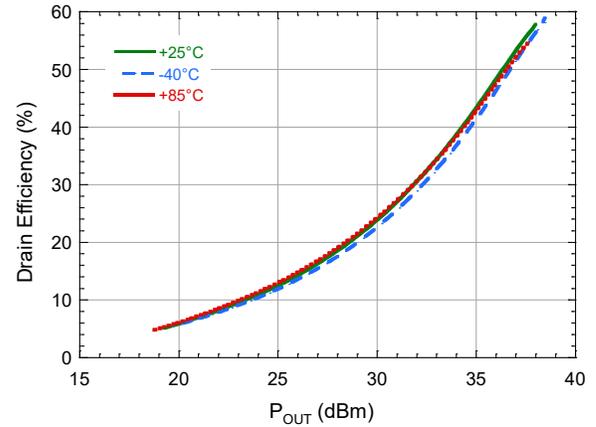
Reference	Value	Tolerance	Manufacturer	Part Number
C1, C6	1.0 $\mu$ F	10%	AVX	12101C105KAT2A
C2, C7	0.1 $\mu$ F	10%	Murata	GRM188R72A104KA35D
C3, C8	0.01 $\mu$ F	10%	AVX	06031C103KAT2A
C4, C9	1000 pF	10%	AVX	06031C102KAT2A
C5	100 $\mu$ F	20%	Panasonic	ECE-V1JA101P
C10, C11	33 pF	5%	ATC	ATC600F330JT
C12	2.4 pF	5%	ATC	ATC600F2R4JT
C13	2.7 pF	5%	ATC	ATC600F2R7JT
C14	3.3 pF	5%	ATC	ATC600F3R3JT
C15	1.5 pF	5%	ATC	ATC600F1R5JT
R1	200 $\Omega$	5%	Panasonic	ERJ-2GEJ201X
R2	0.33 $\Omega$	1%	Susumu	RL1220S-R33-F
PCB	Rogers RO4350, $\epsilon_r = 3.5$ , 20 mil			

Typical Performance as measured in the 2.5 GHz evaluation board:  
CW,  $V_{DS} = 28\text{ V}$ ,  $I_{DQ} = 50\text{ mA}$  (unless noted)

Gain vs. Output Power over Temperature

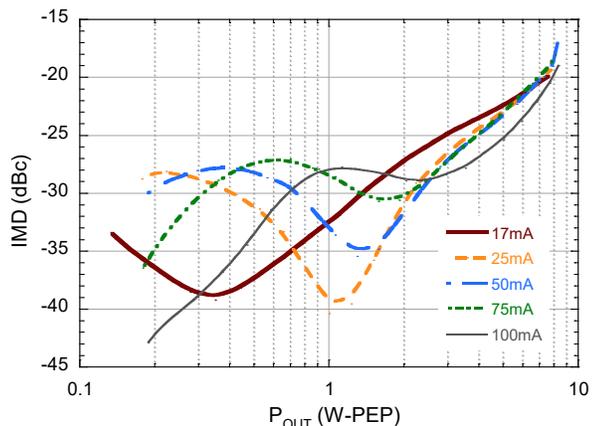


Drain Efficiency vs. Output Power over Temperature

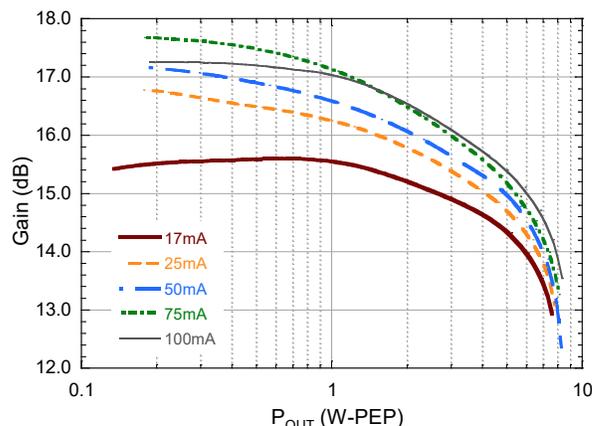


Typical 2-Tone Performance as measured in the 2.5 GHz evaluation board:  
1 MHz Tone Spacing,  $V_{DS} = 28\text{ V}$ ,  $I_{DQ} = 50\text{ mA}$ ,  $T_C = 25^\circ\text{C}$  (unless noted)

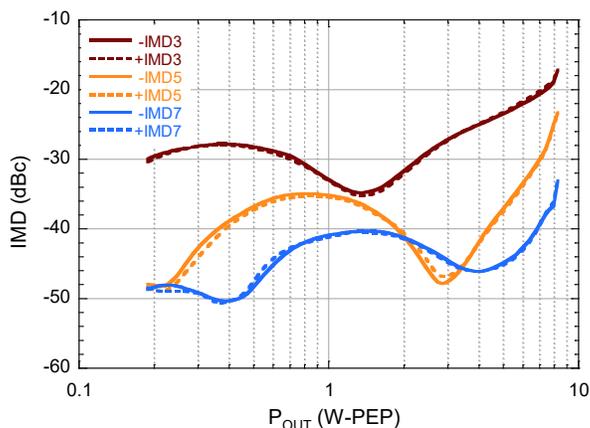
2-Tone IMD3 vs. Output Power vs. Quiescent Current



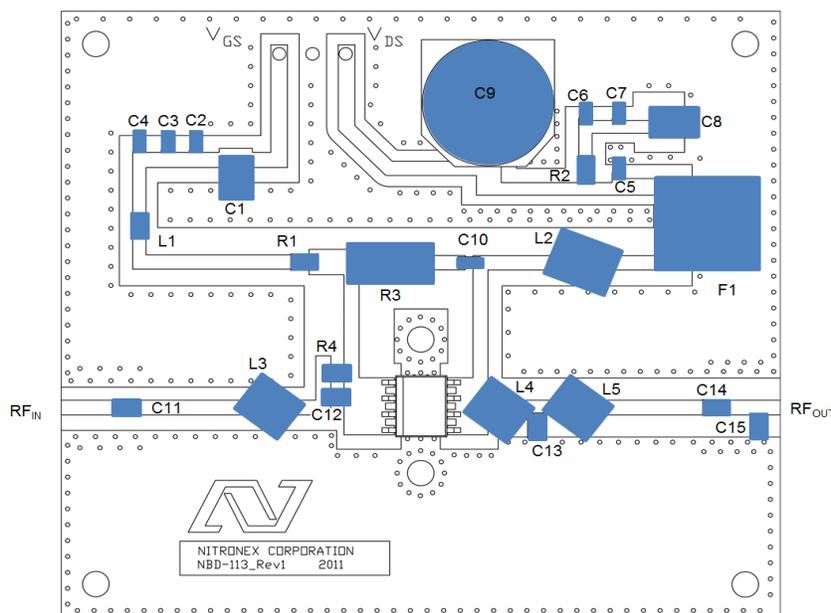
2-Tone Gain vs. Output Power vs. Quiescent Current



2-Tone IMD vs. Output Power



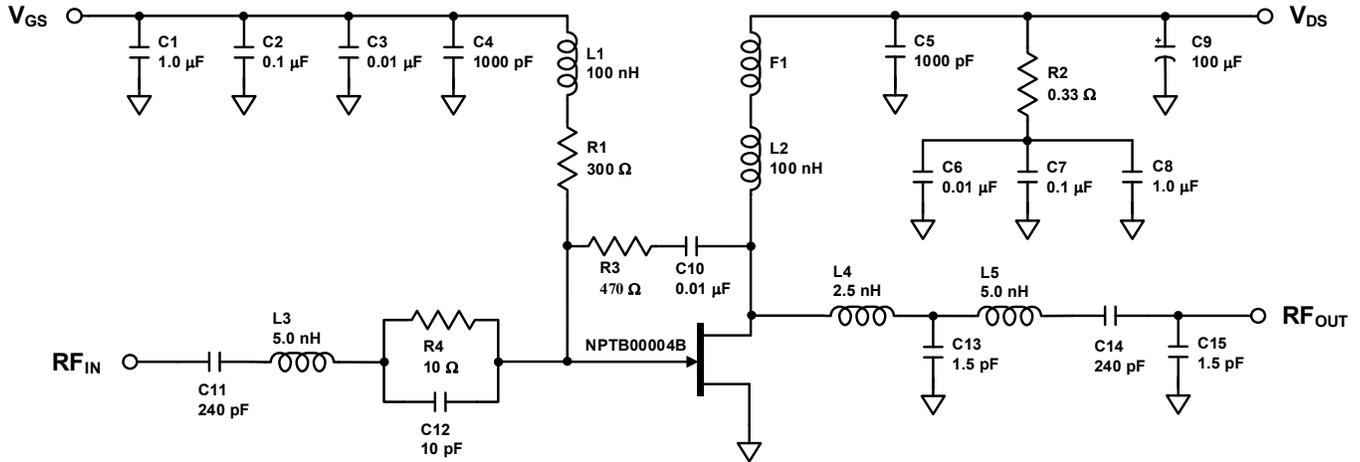
**Evaluation Board and Recommended Tuning Solution**  
100-800 MHz BroadBand Circuit



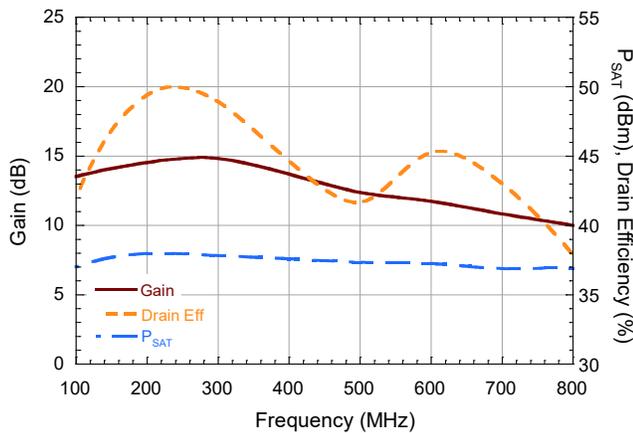
**Parts list**

Reference	Value	Tolerance	Manufacturer	Part Number
C1, C8	1.0 $\mu$ F	10%	AVX	12101C105KAT2A
C2, C7	0.1 $\mu$ F	10%	Murata	GRM188R72A104KA35D
C3, C6, C10	0.01 $\mu$ F	10%	AVX	06031C103KAT2A
C4, C5,	1000 pF	10%	AVX	06031C102KAT2A
C9	100 $\mu$ F	20%	Panasonic	ECE-V1JA101P
C11, C14	240 pF	0.1 pF	ATC	ATC600F241F
C12	10 pF	0.1 pF	ATC	ATC600F100B
C13, C15	1.5 pF	5%	ATC	ATC600F1R5J
F1	Material 73	-	Fair-Rite	2673000801
L1	100 nH	5%	Coilcraft	0805CS-101XJ
L2	100 nH	5%	Coilcraft	1812SMS-R10
L3, L5	5 nH	10%	Coilcraft	A02TKLJ
L4	2.5 nH	10%	Coilcraft	A01TKLJ
R1	300 $\Omega$	5%	Panasonic	ERJ-14YJ301U
R2	0.33 $\Omega$	1%	Susumu	RL1220S-R33-F
R3	470 $\Omega$	1%	Stackpole	RHC2512FT470R
R4	10 $\Omega$	5%	Panasonic	ERJ-14YJ100U
PCB	Rogers RO4350, $\epsilon_r=3.5$ , 0.020"			

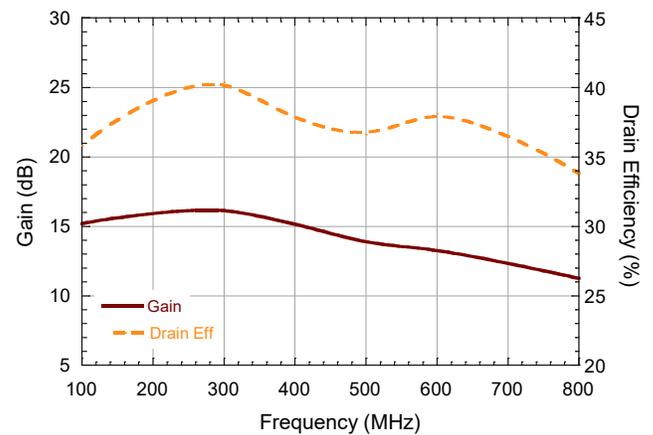
Evaluation Board and Recommended Tuning Solution  
100-800 MHz BroadBand Circuit



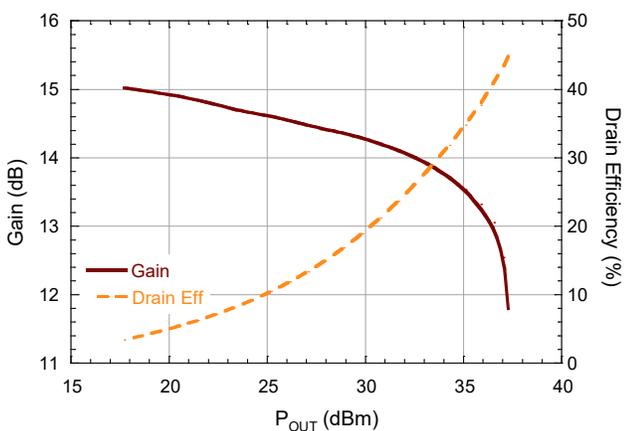
Performance vs. Frequency at  $P_{OUT} = P_{SAT}$



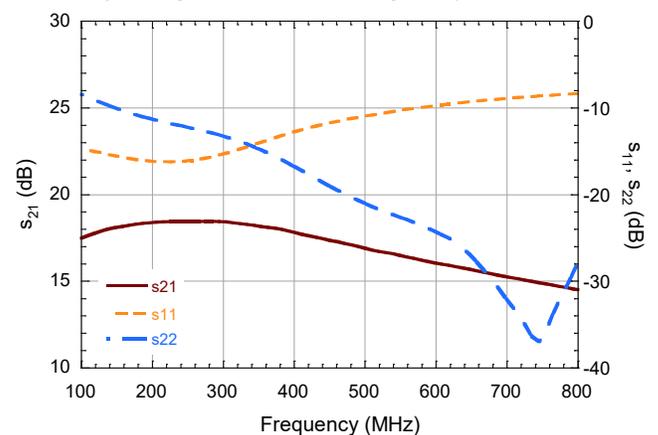
Performance vs. Frequency at  $P_{OUT} = 36$  dBm



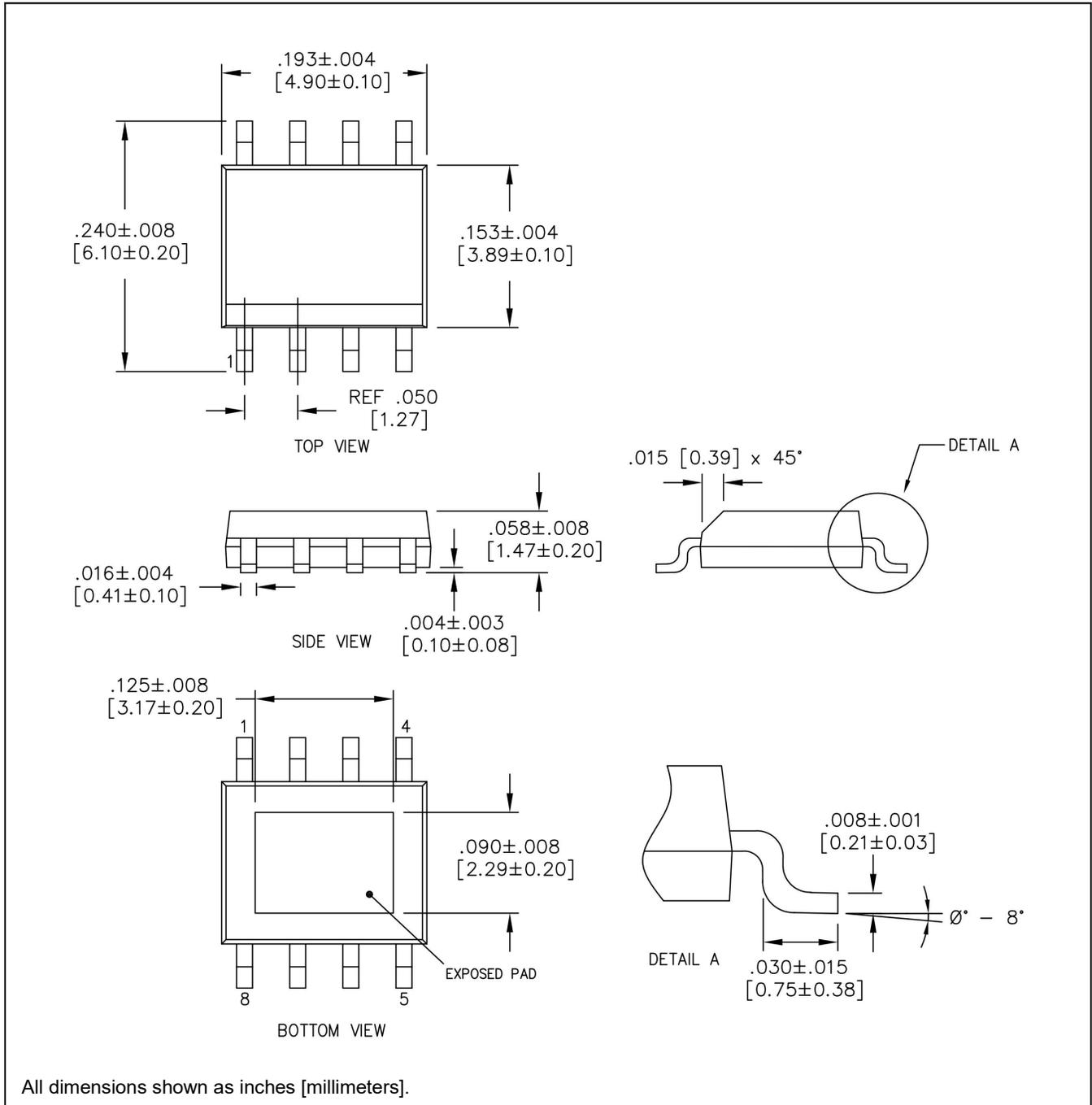
Performance vs. Output Power ( $f = 600$  MHz)



Small Signal s-parameters vs Frequency



SOIC 8-Lead Plastic Package<sup>†</sup>



<sup>†</sup> Meets JEDEC moisture sensitivity level 3 requirements.  
Plating is Matte Sn.

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